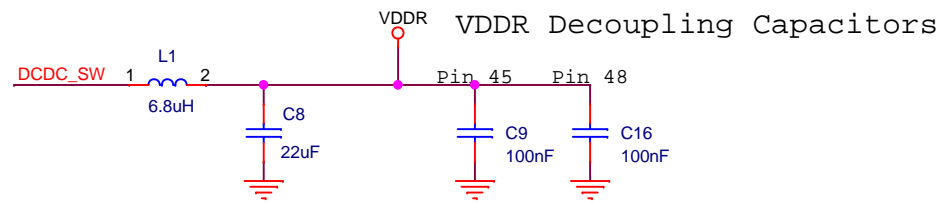
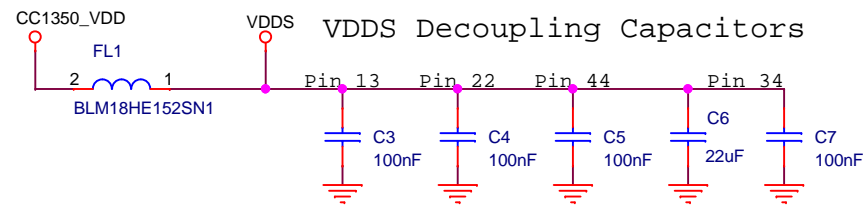


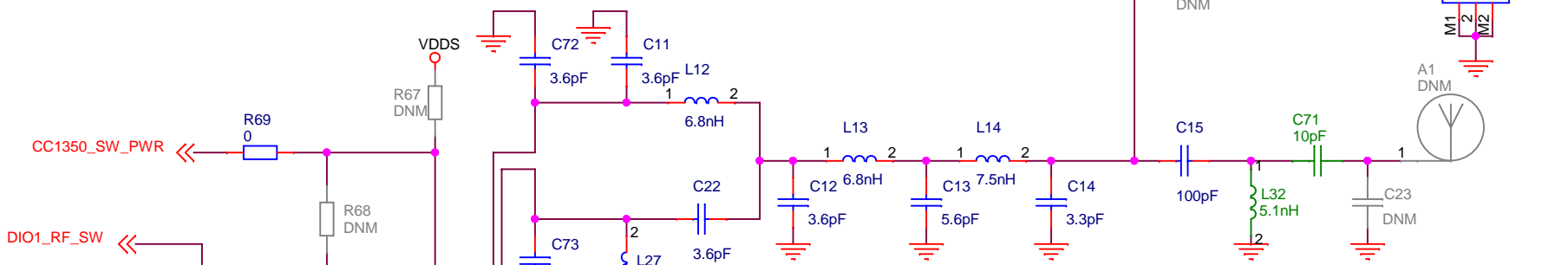
CC1350 RF



Place L1 and C8 close to pin 33

Sub-1 GHz RF section

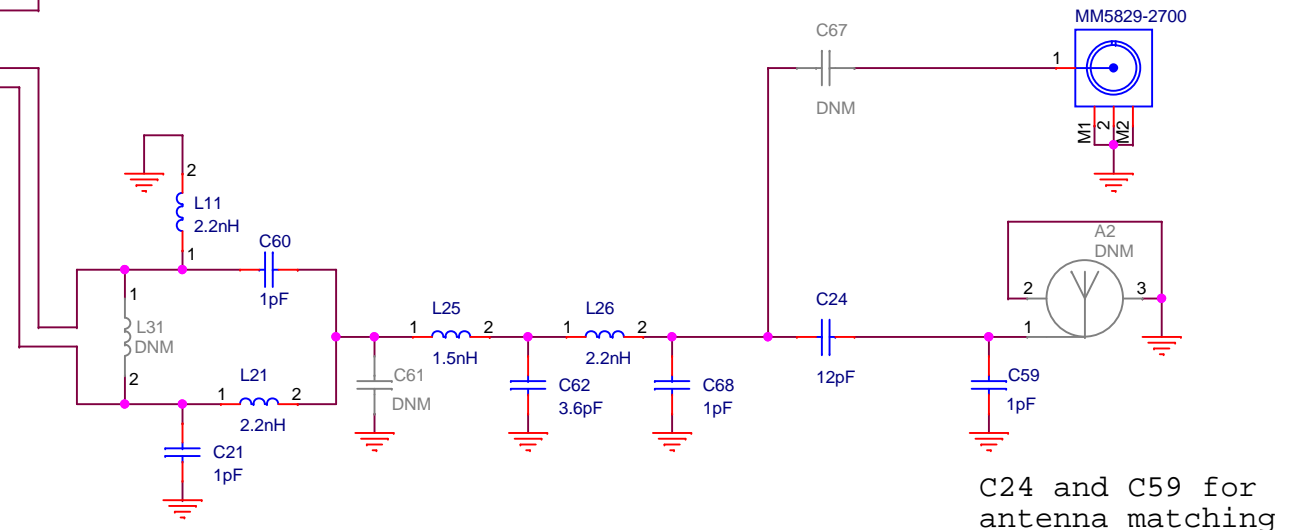
R67, R68, R69 select source of power for RF switch; only mount one of them



L32, C71 and C23 for antenna matching

2.4 GHz RF section

CTL=High selects PORT3
CTL=Low selects PORT2

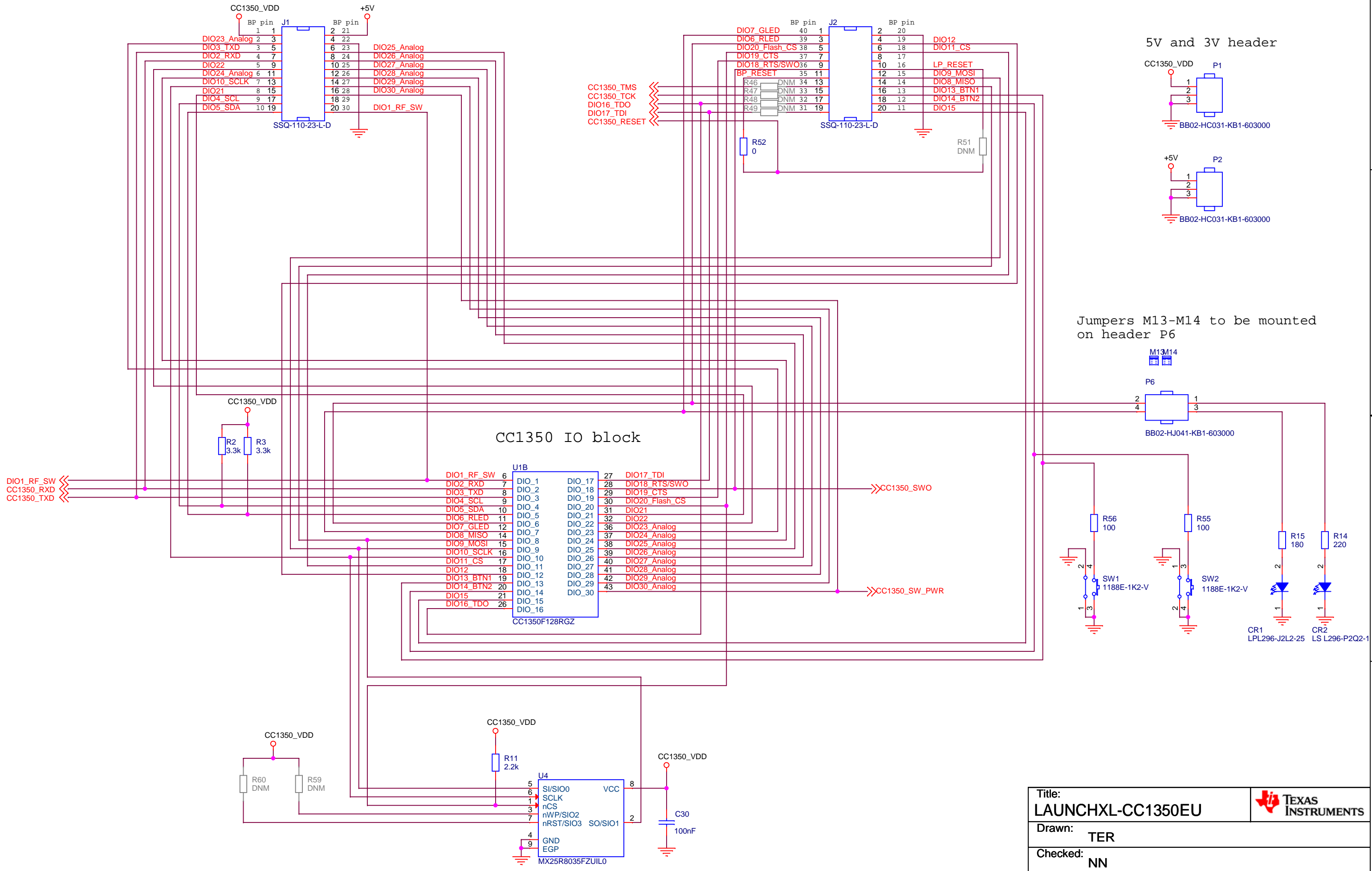


C24 and C59 for antenna matching

CC1350 IO block placed on page 2.

| | | | |
|----------------------------------|------------|-------------------|--|
| Title: LAUNCHXL-CC1350EU | | TEXAS INSTRUMENTS | |
| Drawn: KHT | | | |
| Checked: NN | | | |
| Size: A3 | Rev: 1.3.0 | Sheet: 1 of 5 | |
| Date: Tuesday, November 22, 2016 | | | |

BoosterPack Headers and Peripherals

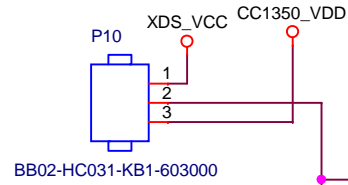


| | | | |
|----------------------------------|------------|-------------------|--|
| Title: LAUNCHXL-CC1350EU | | TEXAS INSTRUMENTS | |
| Drawn: TER | | | |
| Checked: NN | | | |
| Size: A3 | Rev: 1.3.0 | Sheet: 2 of 5 | |
| Date: Tuesday, November 22, 2016 | | | |

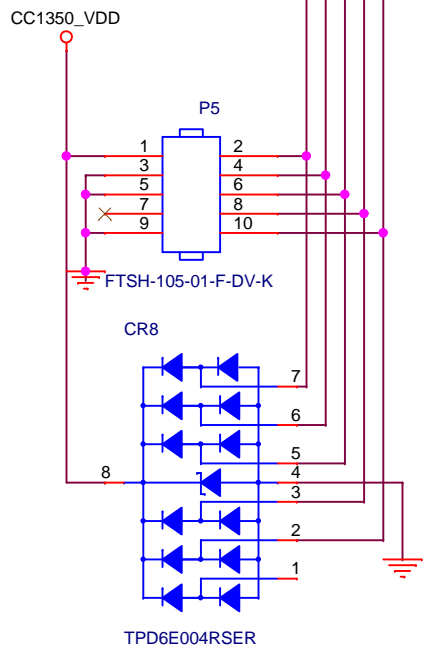
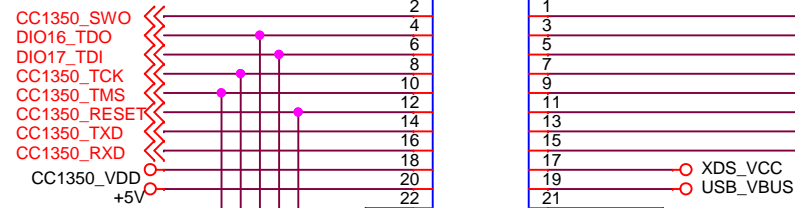
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters
 When powering CC1350 from the XDS suppl, connect jumper between pins 1 and 2.
 When powering CC1350 from the external supply, connect jumper between pins 2 and 3.

Jumper M12 to be mounted
 between pins 1 and 2 on P10

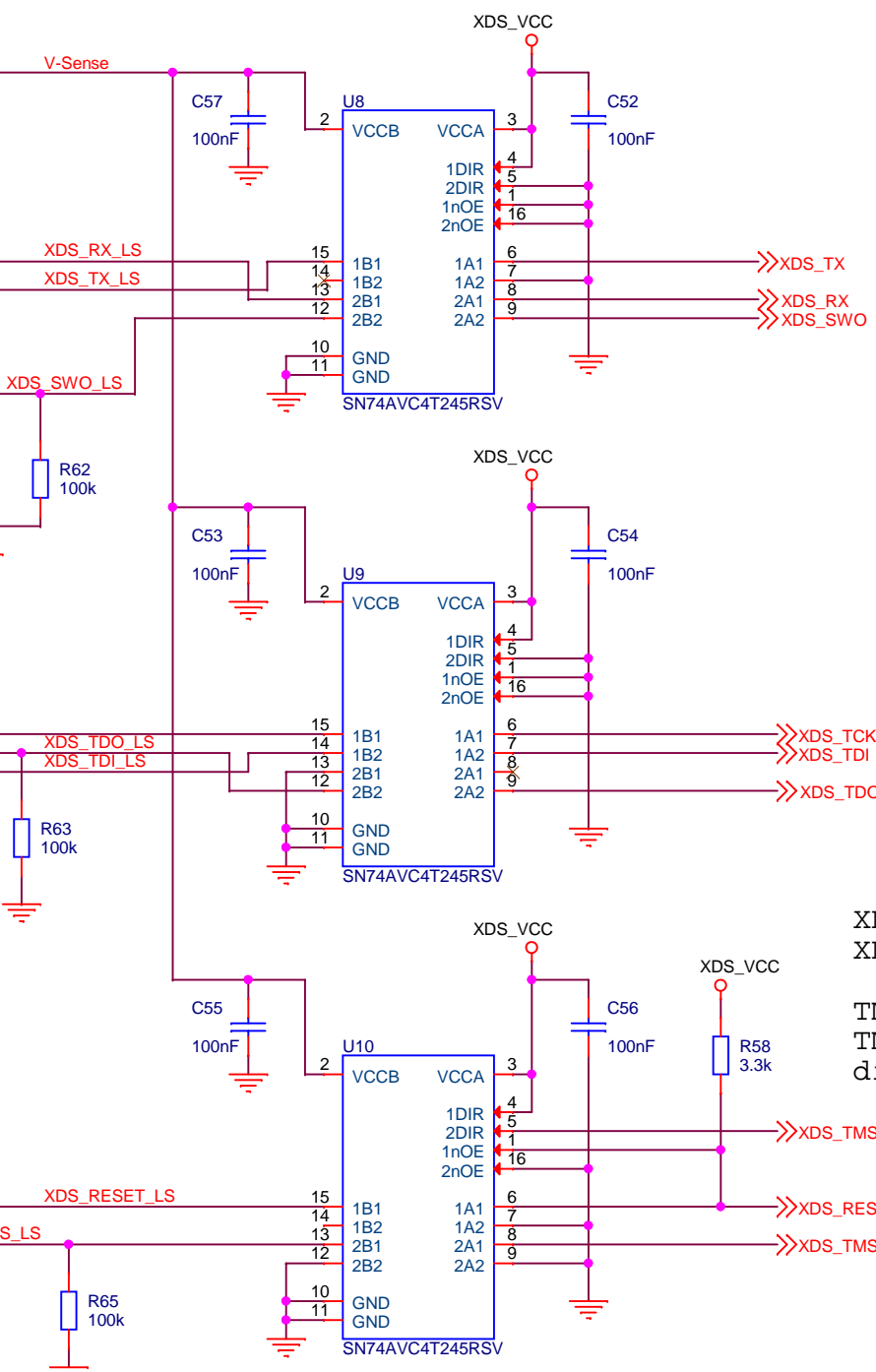
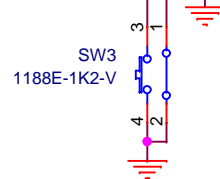
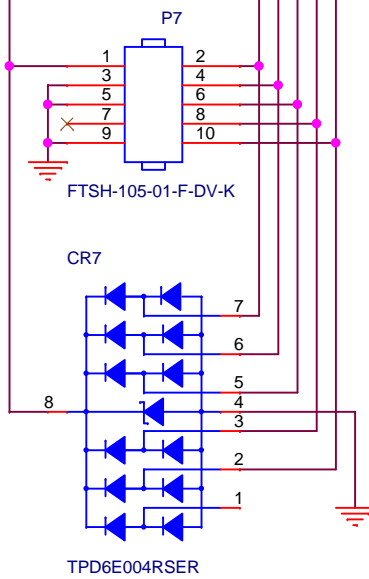


Jumpers M1-M11 to be mounted
 on header P4



Use P5 for debugging
 CC1350 with an
 external debugger
 (requires that all
 jumpers on P4 be
 removed)

Use P7 for debugging
 external targets
 (requires that all
 jumpers on P4 be
 removed)



XDS-RST = 0 -> output = 0
 XDS-RST = 1 -> output = Hi-Z

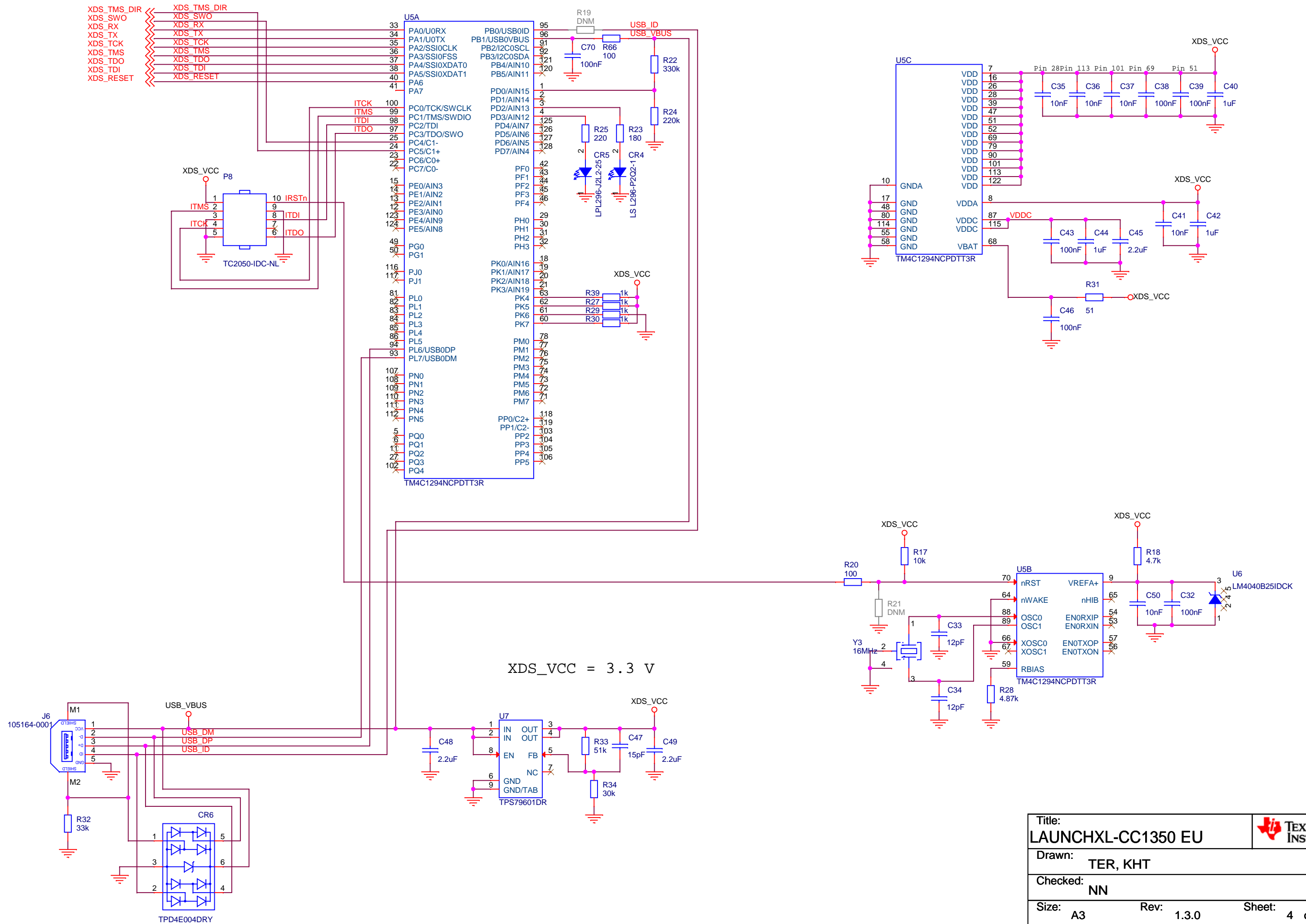
TMS signal is bidirectional.
 TMS_DIR used to control
 direction of level shifter

DIR = H: A -> B
 DIR = L: B -> A

OE = H: output = Hi-Z

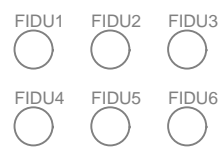
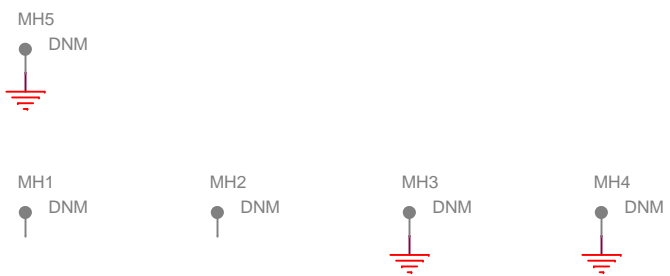
| | | |
|-------------------------------------|---------------|------------------|
| Title: LAUNCHXL-CC1350EU | | |
| Drawn: TER, KHT | | |
| Checked: NN | | |
| Size: A3 | Rev: 1.3.0 | Sheet: 3 of 5 |
| Date: Tuesday, November 22, 2016 | | |


XDS110 Debugger



| | | | | | |
|----------|----------------------------|--------------------|-------|--------|--------|
| Title: | | LAUNCHXL-CC1350 EU | | | |
| Drawn: | | TER, KHT | | | |
| Checked: | | NN | | | |
| Size: | A3 | Rev: | 1.3.0 | Sheet: | 4 of 5 |
| Date: | Tuesday, November 22, 2016 | | | | |

Mechanical



| | | |
|---|-------------------|---|
| Title: LAUNCHXL-CC1350EU | |  |
| Drawn: TER, KHT | | |
| Checked: NN | | |
| Size: A3 | Rev: 1.3.0 | Sheet: 5 of 5 |
| Date: Tuesday, November 22, 2016 | | |

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